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ABSTRACT

5 A method for manufacturing an electronic device comprises a step for forming a coating film (100) on a surface of a conductor portion-containing body (500), a step for forming a photosensitive film (110) on the conductor (500) on which the coating film (100) has been formed, a step for exposing the photosensitive film (110) to a pattern corresponding to a patterned recessed or protruded portion, a step for developing the exposed photosensitive film (110), and a step for baking the developed photosensitive film (110). With this method, an excessive removal of a metal film can be prevented or suppressed.

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